

# 400 MHz to 6 GHz Broadband Quadrature Modulator

## Data Sheet **[ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf)**

### <span id="page-0-0"></span>**FEATURES**

**Output frequency range: 400 MHz to 6 GHz 1 dB output compression: ≥9.4 dBm from 450 MHz to 4 GHz Output return loss ≤ 12 dB from 450 MHz to 4.5 GHz Noise floor: −160 dBm/Hz at 900 MHz Sideband suppression: ≤−50 dBc at 900 MHz Carrier feedthrough: ≤−40 dBm at 900 MHz IQ3dB bandwidth: ≥ 750 MHz Baseband input bias level [ADL5375-05:](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 500 mV [ADL5375-15:](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 1500 mV** 

**Single supply: 4.75 V to 5.25 V 24-lead LFCSP\_VQ package** 

#### <span id="page-0-1"></span>**APPLICATIONS**

**Cellular communication systems GSM/EDGE, CDMA2000, W-CDMA, TD-SCDMA WiMAX/LTE broadband wireless access systems Satellite modems** 

#### <span id="page-0-3"></span>**GENERAL DESCRIPTION**

Th[e ADL5375 i](http://www.analog.com/ADL5375?doc=ADL5375.pdf)s a broadband quadrature modulator designed for operation from 400 MHz to 6 GHz. Its excellent phase accuracy and amplitude balance enable high performance intermediate frequency or direct radio frequency modulation for communication systems.

The [ADL5375 f](http://www.analog.com/ADL5375?doc=ADL5375.pdf)eatures a broad baseband bandwidth, along with an output gain flatness that varies no more than 1 dB from 450 MHz to 3.5 GHz. These features, coupled with a broadband output return loss of ≤−12 dB, make the [ADL5375 i](http://www.analog.com/ADL5375?doc=ADL5375.pdf)deally suited for broadband zero IF or low IF-to-RF applications,

#### **FUNCTIONAL BLOCK DIAGRAM**

<span id="page-0-2"></span>

broadband digital predistortion transmitters, and multiband radio designs.

The [ADL5375 a](http://www.analog.com/ADL5375?doc=ADL5375.pdf)ccepts two differential baseband inputs and a single-ended LO. It generates a single-ended 50  $\Omega$  output. The two versions offer input baseband bias levels of 500 mV [\(ADL5375-05\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf) and 1500 mV [\(ADL5375-15\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf).

The [ADL5375 i](http://www.analog.com/ADL5375?doc=ADL5375.pdf)s fabricated using an advanced silicon-germanium bipolar process. It is available in a 24-lead, exposed paddle, leadfree, LFCSP\_VQ package. Performance is specified over a −40°C to +85°C temperature range. A lead-free evaluation board is also available.

#### **Rev. D [Document Feedback](https://form.analog.com/Form_Pages/feedback/documentfeedback.aspx?doc=ADL5375.pdf&product=ADL5375&rev=D)**

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#### **9/11—Rev. A to Rev. B**







### **11/08—Rev. 0 to Rev. A**



**12/07—Revision 0: Initial Version**

## <span id="page-2-0"></span>**SPECIFICATIONS**

 $V_S = 5 V$ ; T<sub>A</sub> = 25°C; LO = 0 dBm single-ended drive; baseband I/Q amplitude = 1 V p-p differential sine waves in quadrature with a 500 mV [\(ADL5375-05\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf) or 1500 mV [\(ADL5375-15\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf) dc bias; baseband I/Q frequency ( $f_{BB}$ ) = 1 MHz, unless otherwise noted.

#### **Table 1.**









<sup>1</sup> The input bias level can vary as long as the voltages on the individual IBBP, IBBN, QBBP, and QBBN pins remain within the specified absolute voltage level.

## <span id="page-6-0"></span>ABSOLUTE MAXIMUM RATINGS

#### **Table 2.**



<sup>1</sup> Per JDEC standard JESD 51-2. For information on optimizing thermal impedance, see th[e Thermal Grounding and Evaluation Board Layout](#page-31-0) section.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### <span id="page-6-1"></span>**ESD CAUTION**



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

## <span id="page-7-0"></span>PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



Figure 2. Pin Configuration

#### **Table 3. Pin Function Descriptions**



## <span id="page-8-0"></span>TYPICAL PERFORMANCE CHARACTERISTICS

### <span id="page-8-1"></span>**[ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf)**

 $V_S = 5 V$ ; T<sub>A</sub> = 25°C; LO = 0 dBm single-ended drive; baseband I/Q amplitude = 1 V p-p differential sine waves in quadrature with a 500 mV dc bias; baseband I/Q frequency ( $f_{BB}$ ) = 1 MHz, unless otherwise noted.



Figure 5. SSB Output 1dB Compression Point (OP1dB) vs. LO Frequency (f<sub>LO</sub>) and Temperature



Figure 6. SSB Output 1dB Compression Point (OP1dB) vs. LO Frequency ( $f_{LO}$ ) and Supply



<span id="page-8-2"></span>Figure 7. Smith Chart of LOIP (LOIN AC-Coupled to Ground) S11 and RFOUT S22 from 450 MHz to 6000 MHz



Figure 8. Return Loss of LOIP (LOIN AC-Coupled to Ground) S11 and RFOUT S22 from 450 MHz to 6000 MHz



Figure 9. Carrier Feedthrough vs. LO Frequency ( $f<sub>LO</sub>$ ) and Temperature; Multiple Devices Shown

![](_page_9_Figure_4.jpeg)

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Figure 12. Sideband Suppression vs. LO Frequency ( $f<sub>LO</sub>$ ) and Temperature After Nulling at 25°C; Multiple Devices Shown

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Figure 13. Second- and Third-Order Distortion, Carrier Feedthrough, Sideband Suppression, and SSB Pout vs. Baseband Differential Input Level  $(f_{LO} = 900 MHz)$ 

![](_page_9_Figure_12.jpeg)

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![](_page_10_Figure_1.jpeg)

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![](_page_10_Figure_3.jpeg)

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![](_page_10_Figure_5.jpeg)

![](_page_10_Figure_6.jpeg)

![](_page_10_Figure_7.jpeg)

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![](_page_10_Figure_9.jpeg)

![](_page_10_Figure_10.jpeg)

![](_page_10_Figure_11.jpeg)

Figure 20. Second- and Third-Order Distortion, Carrier Feedthrough, Sideband Suppression, and SSB Pout vs. LO Amplitude ( $f_{LO}$  = 900 MHz)

![](_page_11_Figure_2.jpeg)

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![](_page_11_Figure_6.jpeg)

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![](_page_11_Figure_8.jpeg)

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![](_page_11_Figure_10.jpeg)

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![](_page_11_Figure_12.jpeg)

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![](_page_12_Figure_2.jpeg)

<span id="page-12-0"></span>Figure 27. SSB  $P_{\text{OUT}}$  Isolation and Carrier Feedthrough with DSOP High

### <span id="page-13-0"></span>**[ADL5375-15](http://www.analog.com/ADL5375?doc=ADL5375.pdf)**

 $V_S = 5 V$ ; T<sub>A</sub> = 25°C; LO = 0 dBm single-ended drive; baseband I/Q amplitude = 1 V p-p differential sine waves in quadrature with a 1500 mV dc bias; baseband I/Q frequency ( $f_{BB}$ ) = 1 MHz, unless otherwise noted.

![](_page_13_Figure_4.jpeg)

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![](_page_13_Figure_6.jpeg)

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![](_page_13_Figure_8.jpeg)

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![](_page_13_Figure_10.jpeg)

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<span id="page-13-1"></span>Figure 32. Smith Chart of LOIP (LOIN AC-Coupled to Ground) S11 and RFOUT S22 from 450 MHz to 6000 MHz

![](_page_13_Figure_14.jpeg)

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![](_page_14_Figure_1.jpeg)

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![](_page_14_Figure_3.jpeg)

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![](_page_14_Figure_7.jpeg)

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![](_page_14_Figure_9.jpeg)

Figure 38. Second- and Third-Order Distortion, Carrier Feedthrough, Sideband Suppression, and SSB  $P_{OUT}$  vs. Baseband Differential Input Level  $(f_{LO} = 900 \, MHz)$ 

![](_page_14_Figure_11.jpeg)

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![](_page_15_Figure_3.jpeg)

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![](_page_15_Figure_5.jpeg)

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![](_page_15_Figure_10.jpeg)

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![](_page_15_Figure_12.jpeg)

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![](_page_16_Figure_1.jpeg)

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![](_page_16_Figure_3.jpeg)

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![](_page_16_Figure_5.jpeg)

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![](_page_16_Figure_7.jpeg)

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![](_page_16_Figure_9.jpeg)

Figure 50. 20 MHz Offset Noise Floor Distribution at  $f_{LO} = 2140$  MHz (I/Q Amplitude =  $0$  mV p-p with 1500 mV DC Bias)

![](_page_16_Figure_11.jpeg)

Figure 51. 20 MHz Offset Noise Floor Distribution at  $f_{LO} = 3500$  MHz (I/Q Amplitude =  $0$  mV p-p with 500 mV DC Bias)

![](_page_17_Figure_2.jpeg)

<span id="page-17-0"></span>Figure 52. SSB  $P_{OUT}$  Isolation and Carrier Feedthrough with DSOP High

## <span id="page-18-0"></span>THEORY OF OPERATION **CIRCUIT DESCRIPTION**

<span id="page-18-1"></span>The [ADL5375 c](http://www.analog.com/ADL5375?doc=ADL5375.pdf)an be divided into five circuit blocks: the LO interface, the baseband voltage-to-current (V-to-I) converter, the mixers, the differential-to-single-ended (D-to-S) stage, and the bias circuit. A block diagram of the device is shown in [Figure 53.](#page-18-2) 

![](_page_18_Figure_4.jpeg)

<span id="page-18-2"></span>The LO interface generates two LO signals in quadrature. These signals are used to drive the mixers. The I/Q baseband input signals are converted to currents by the V-to-I stages, which then drive the two mixers. The outputs of these mixers combine to feed the output balun, which provides a singleended output. The bias cell generates reference currents for the V-to-I stage.

### **LO Interface**

The LO interface consists of a polyphase quadrature splitter and a limiting amplifier. The LO input impedance is set by the polyphase splitter. Each quadrature LO signal then passes through a limiting amplifier that provides the mixer with a limited drive signal.

The LO input can be driven single-ended or differentially. For applications above 3 GHz, improved OIP2 and LO leakage may result from driving the LO input differentially.

### **V-to-I Converter**

The differential baseband inputs (QBBP, QBBN, IBBN, and IBBP) present a high impedance. The voltages applied to these pins drive the V-to-I stage that converts baseband voltages into currents. The differential output currents of the V-to-I stages feed each of their respective mixers. The dc common-mode voltage at the baseband inputs sets the currents in the two mixer cores. Varying the baseband common-mode voltage influences the current in the mixer and affects overall modulator performance. The recommended dc voltage for the baseband common-mode voltage is 500 mV dc for th[e ADL5375-05 a](http://www.analog.com/ADL5375?doc=ADL5375.pdf)nd 1500 mV for th[e ADL5375-15.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 

### **Mixers**

The [ADL5375 h](http://www.analog.com/ADL5375?doc=ADL5375.pdf)as two double-balanced mixers: one for the in-phase channel (I channel) and one for the quadrature channel (Q-channel). The output currents from the two mixers sum together into an internal load. The signal developed across this load is used to drive the D-to-S stage.

### **D-to-S Stage**

The output D-to-S stage consists of an on-chip active balun that converts the differential signal to a single-ended signal. The balun presents 50  $\Omega$  impedance to the output (VOUT). Therefore, no matching network is needed at the RF output for optimal power transfer in a 50  $\Omega$  environment.

### **Bias Circuit**

An on-chip band gap reference circuit is used to generate a proportional-to-absolute temperature (PTAT) reference current for the V-to-I stage.

### **DSOP**

The DSOP pin can be used to disable the output stage of the modulator. If the DSOP pin is connected to ground or left unconnected, the part operates normally. If the DSOP pin is connected to the positive voltage supply, the output stage is disabled and the LO leakage is also reduced.

## <span id="page-19-0"></span>BASIC CONNECTIONS

![](_page_19_Figure_3.jpeg)

Figure 54. Basic Connections for th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 

<span id="page-19-5"></span>[Figure 54 s](#page-19-5)hows the basic connections for the [ADL5375.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 

### <span id="page-19-1"></span>**POWER SUPPLY AND GROUNDING**

Pin VPS1 and Pin VPS2 should be connected to the same 5 V source. Each pin should be decoupled with a 100 pF and 0.1 μF capacitor. These capacitors should be located as close as possible to the device. The power supply can range between 4.75 V and 5.25 V.

The ten COMM pins should be tied to the same ground plane through low impedance paths.

The exposed paddle on the underside of the package should also be soldered to a ground plane with low thermal and electrical impedance. If the ground plane spans multiple layers on the circuit board, they should be stitched together with nine vias under the exposed paddle as illustrated in th[e Evaluation](#page-29-0)  [Board](#page-29-0) section. The [AN-772 A](http://www.analog.com/AN-772?doc=ADL5375.pdf)pplication Note discusses the thermal and electrical grounding of the LFCSP (QFN) package in detail.

### <span id="page-19-2"></span>**BASEBAND INPUTS**

The baseband inputs (IBBP, IBBN, QBBP, and QBBN) should be driven from a differential source. The nominal drive level used in the characterization of th[e ADL5375 i](http://www.analog.com/ADL5375?doc=ADL5375.pdf)s 1 V p-p differential (or 500 mV p-p on each pin).

All the baseband inputs must be externally dc biased. The recommended common-mode level is dependent on the version of the [ADL5375.](http://www.analog.com/ADL5375?doc=ADL5375.pdf)

- [ADL5375-05:](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 500 mV
- [ADL5375-15:](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 1500 mV

### <span id="page-19-3"></span>**LO INPUT**

The LO input is designed to be driven from a single-ended source. The LO source is ac-coupled through a series capacitor to the LOIP pin while the LOIN pin is ac-coupled to ground through a second capacitor.

The typical LO drive level, which was used for the characterization of the [ADL5375,](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is 0 dBm.

Differential operation is also possible, in which case both sides of the differential LO source should be ac-coupled through a pair of series capacitors to the LOIP and LOIN pins.

### <span id="page-19-4"></span>**RF OUTPUT**

The RF output is available at the RFOUT pin (Pin 16), which can drive a 50  $\Omega$  load. The internal balun provides a low dc path to ground. In most situations, the RFOUT pin must be ac-coupled to the load.

### <span id="page-20-0"></span>**OUTPUT DISABLE**

The [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) incorporates an output disable pin feature that shuts down the output amplifier stage to isolate the modulator from the load. This output is disabled when the voltage on the DSOP exceeds 2 V. The output is enabled when the DSOP pin is either tied to ground or left unconnected.

Asserting DSOP further reduces LO leakage (see [Figure 27](#page-12-0) and [Figure 52\)](#page-17-0) and drives the broadband noise of the device down

to just above the KT thermal noise level. Asserting DSOP also reduces the supply current of the [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) from 200 mA to 127 mA.

The time delay between when DSOP pin going low and the output power being restored is approximately 200 ns. The time delay when DSOP going high and output being disabled is less than 100 ns.

## <span id="page-21-1"></span><span id="page-21-0"></span>APPLICATIONS INFORMATION **CARRIER FEEDTHROUGH NULLING**

LO leakage results from minute dc offsets that occur on the differential baseband inputs. In an IQ modulator, non-zero differential offsets mix with the LO and result in LO leakage to the RF output. In addition to this effect, some of the signal power at the LO input couples directly to the RF output (this may be a result of bond-wire to bond-wire coupling or coupling through the silicon substrate). The net LO leakage at the RF output is the vector combination of the signals that appear at the output as a result of these two effects.

The device's nominal carrier feedthrough can be nulled by adding small external differential offset voltages on the I and Q inputs.

Nulling the carrier feedthrough is a multistep process. Initially, with the I-channel offset held constant (at 0 mV), the Qchannel offset is varied until a minimum LO leakage level is obtained. This Q-channel offset voltage is then held constant, while the offset on the I-channel is adjusted until a new minimum is reached. Through two iterations of this process, the LO leakage can be reduced to an arbitrarily low level. This level is only limited by the available offset voltage steps and by the modulator's noise floor[. Figure 55](#page-21-3) illustrates the typical relationship between LO leakage and dc offset at 1900 MHz. In this case, differential offset voltages of approximately +0.5 mV and −0.5 mV on the I and Q inputs, respectively, result in the lowest carrier feedthrough. It is important to note that the required offset nulling voltage changes in polarity and magnitude from device to device and overtemperature and frequency. To ensure that all devices in a mass production environment can be adequately nulled, an offset adjustment range of approximately ±10 mV should be provided.

![](_page_21_Figure_6.jpeg)

<span id="page-21-3"></span>Figure 55. Example of Typical Carrier Feedthrough vs. DC Offset Voltage

It is important to note that the carrier feedthrough is not affected by the dc bias levels (also called the common-mode level) on the I and Q inputs. A differential offset voltage must be applied, so after nulling, the average voltage on the IP and

IN inputs can be slightly different. Using [Figure 55](#page-21-3) as an example, after LO leakage nulling, the average dc level on IP and IN can be 500.25 mV and 499.75 mV.

The same applies to the Q-channel. For the [ADL5375-15,](http://www.analog.com/ADL5375?doc=ADL5375.pdf) the same theory applies except that

 $V_{IBBP} = V_{IBBN} = 1500$  mV.

It is often desirable to perform a one-time carrier null. This is usually performed at a given frequency. After this factory calibration, the IQ modulator operates over a frequency range on each side of the calibration frequency. The nulled LO leakage level degrades somewhat because the LO frequency is moved away from the calibration frequency. Despite this degradation, the overall LO leakage across a frequency band can be expected to be better than when no nulling is performed. This assumes an operating frequency band that is in the 30 MHz to 60 MHz range.

LO leakage nulling is discussed further i[n AN-1039,](http://www.analog.com/AN-1039?doc=AD5375.pdf) Correcting Imperfections in IQ Modulators to Improve RF Signal Fidelity.

### <span id="page-21-2"></span>**SIDEBAND SUPPRESSION OPTIMIZATION**

Sideband suppression results from relative gain and relative phase offsets between the I-channel and Q-channel and can be suppressed through adjustments to those two parameters. [Figure 56](#page-21-4) illustrates how sideband suppression is affected by the gain and phase imbalances.

![](_page_21_Figure_16.jpeg)

<span id="page-21-4"></span>Figure 56. Sideband Suppression vs. Quadrature Phase Error for Various Quadrature Amplitude Offsets

[Figure 56](#page-21-4) underlines the fact that adjusting only one parameter improves the sideband suppression only to a point, unless the other parameter is also adjusted. For example, if the amplitude offset is 0.25 dB, improving the phase imbalance by better than 1° does not yield any improvement in the sideband suppression. For optimum sideband suppression, an iterative adjustment between phase and amplitude is required.

The sideband suppression nulling can be performed either through adjusting the gain for each channel or through the modification of the phase and gain of the digital data coming from the baseband signal processor.

Sideband suppression is discussed further in [AN-1100,](http://www.analog.com/AN-1100?doc=ADL5375.pdf) Wireless Transmitter IQ Balance and Sideband Suppression, as well as in [AN-1039,](http://www.analog.com/AN-1039?doc=ADL5375.pdf) Correcting Imperfections in IQ Modulators to Improve RF Signal Fidelity.

### <span id="page-22-0"></span>**INTERFACING THE [ADF4350](http://www.analog.com/ADF4350?doc=ADL5375.pdf) PLL TO THE [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf)**

With an output frequency range of 137.5 to 4.4 GHz, a high performance integrated VCO and an LO output power level that can be programmed from −4 dBm to +5 dBm, the [ADF4350](http://www.analog.com/ADF4350?doc=ADL5375.pdf) wideband synthesizer is ideally suited to drive the [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) LO port.

Care must be taken to adequately suppress the harmonics of the LO signal from the PLL. VCOs typically have a third harmonic power of approximately −10 dBc. A large third harmonic on the LO degrades the quality of the quadrature generation inside the IQ Modulator. The third harmonic should be suppressed to a level of –30 dBc or lower to prevent quadrature degradation. So approximately 20 dB of attenuation is required to get the third harmonic below −30 dBc. [Figure 57](#page-22-1) shows PLL modulator interfaces schematic that for this operation at four different frequencies, and [Table 4](#page-22-2) shows the optimized components value o[f Figure 57.](#page-22-1) Because filtering of the third harmonic is most critical, and to ensure wide frequency range coverage, the 3 dB corner of the filters have been set to approximately 1.2~1.5 times the maximum desired LO frequency. A Chebyshev filter topology at 100 Ω differential source impedance and 50  $Ω$ differential load impedance was used for optimal performance.

![](_page_22_Figure_7.jpeg)

<span id="page-22-1"></span>Figure 57. PLL-Modulator Interface Schematic

<span id="page-22-2"></span>![](_page_22_Picture_297.jpeg)

![](_page_22_Picture_298.jpeg)

The two pull-up inductors of the Zbias provide two 50  $\Omega$  source impedances in combination with R1 resistor in parallel for the filter. While th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is specified to be driven by a singleended LO, the LOIP and LOIN input pins are naturally differential. Therefore, the differential LO drive from the [ADF4350 i](http://www.analog.com/ADF4350?doc=ADL5375.pdf)s more desirable.

The output power from th[e ADF4350](http://www.analog.com/ADF4350?doc=ADL5375.pdf) can be set to −4 dBm, −1 dBm,+2 dBm, and +5 dBm using Register 4 Bits[D2:D1] and −6 dBm to +7 dBm LO drive level fo[r ADL5375 i](http://www.analog.com/ADL5375?doc=ADL5375.pdf)s recommended.

If the physical distance between the PLL and the IQ modulator is significant, the filter should be placed adjacent to the IQ modulator, and two 50  $\Omega$  traces should be run between the devices (since there is a 50  $\Omega$  impedance looking from each of the filter inputs back to each of the PLL outputs).

The [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) evaluation board can be reconfigured for differential drive and also includes component pads in its LO path to accommodate a harmonic filter. Th[e ADF4350 e](http://www.analog.com/ADF4350?doc=ADL5375.pdf)valuation board can also be configured to provide a differential output and can be connected directly to the [ADL5375 e](http://www.analog.com/ADL5375?doc=ADL5375.pdf)valuation board.

Optimizing the interface between a PLL LO and I/Q modulator is discussed further in CN-0134 Broadband Low EVM Direct Conversion Transmitter: How to Optimize the Interface Between a PLL LO and I/Q Modulator.

### <span id="page-23-0"></span>**DAC MODULATOR INTERFACING**

### **Driving th[e ADL5375-05 w](http://www.analog.com/ADL5375?doc=ADL5375.pdf)ith a TXDAC®**

The [ADL5375-05 i](http://www.analog.com/ADL5375?doc=ADL5375.pdf)s designed to interface with minimal components to members of the Analog Devices, Inc. TxDAC families. These dual-channel differential current output DACs feature an output current swing from 0 mA to 20 mA. The interface described in this section can be used with any DAC that has a similar output.

An example of an interface using the [AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) TxDAC is shown in [Figure 58.](#page-23-1) The baseband inputs of th[e ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) require a dc bias of 500 mV. The nominal midscale current on each of the outputs of th[e AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) is 10 mA. Therefore, a single 50  $\Omega$ resistor to ground from each of the DAC outputs results in an average current of 10 mA flowing through each of the resistors, thus producing the desired 500 mV dc bias for the inputs to the [ADL5375-05.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 

![](_page_23_Figure_11.jpeg)

<span id="page-23-1"></span>Figure 58. Interface Between th[e AD9122 a](http://www.analog.com/AD9122?doc=ADL5375.pdf)n[d ADL5375-05 w](http://www.analog.com/ADL5375?doc=ADL5375.pdf)ith 50 Ω Resistors to Ground to Establish the 500 mV DC Bias for th[e ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf)  Baseband Inputs

Th[e AD9122 o](http://www.analog.com/AD9122?doc=ADL5375.pdf)utput currents have a swing that ranges from 0 mA to 20 mA. With the 50  $\Omega$  resistors in place, the ac voltage swing going into th[e ADL5375-05 b](http://www.analog.com/ADL5375?doc=ADL5375.pdf)aseband inputs ranges from 0 V to 1 V. A full-scale sine wave out of th[e AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) can be described as a 1 V p-p single-ended (or 2 V p-p differential) sine wave with a 500 mV dc bias.

#### <span id="page-23-3"></span>**Limiting the AC Swing**

There are situations in which it is desirable to reduce the ac voltage swing for a given DAC output current. This can be achieved through the addition of another resistor to the interface. This resistor is placed in the shunt between each side of the differential pair, as shown i[n Figure 59.](#page-23-2) It has the effect of reducing the ac swing without changing the dc bias already established by the 50  $\Omega$  resistors.

![](_page_23_Figure_16.jpeg)

<span id="page-23-2"></span>Figure 59. AC Voltage Swing Reduction Through the Introduction of a Shunt Resistor Between Differential Pair

The value of this ac voltage swing limiting resistor is chosen based on the desired ac voltage swing[. Figure 60](#page-24-0) shows the relationship between the swing-limiting resistor and the peakto-peak ac swing that it produces when 50  $\Omega$  bias-setting resistors are used. The differential peak-to-peak swing at the modulator input is

![](_page_24_Figure_2.jpeg)

<span id="page-24-0"></span>Figure 60. Relationship Between the AC Swing-Limiting Resistor and the Peak-to-Peak Voltage Swing with 50 Ω Bias-Setting Resistors

#### **Filtering**

It is necessary to place an antialiasing filter between the DAC and modulator to filter out Nyquist images, common mode noise, and broadband DAC noise. The interface for setting up the biasing and ac swing discussed in the [Limiting the AC](#page-23-3)  [Swing](#page-23-3) section lends itself well to the introduction of such a filter. The filter can be inserted between the dc bias setting resistors and the ac swing-limiting resistor. With this configuration, the dc bias setting resistors and the signal scaling resistors conveniently set the source and load resistances for the filter.

[Figure 61](#page-24-1) shows a third-order, Bessel low-pass filter with a 3 dB frequency of 10 MHz. Matching input and output impedances make the filter design easier, so the shunt resistor chosen is 100 Ω, producing an ac swing of 1 V p-p differential. The frequency response of this filter is shown in [Figure 62.](#page-24-2) 

![](_page_24_Figure_7.jpeg)

<span id="page-24-1"></span>10 MHz Third-Order, Bessel Filter

![](_page_24_Figure_9.jpeg)

<span id="page-24-2"></span>Figure 62. Frequency Response for DAC Modulator Interface with 10 MHz Third-Order Bessel Filter

#### **Complex IF Operation**

The [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) can be used with a DAC, generating a complex-IF (CIF), as well as a zero-IF signal (ZIF). The −1 dB bandwidth of the [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is approximately more than 400 MHz [\(Figure 63](#page-24-3) an[d Figure 64](#page-25-0) show the baseband frequency response of the [ADL5375,](http://www.analog.com/ADL5375?doc=ADL5375.pdf) facilitating high CIF and providing sufficient flat bandwidth for digital predistortion (DPD) algorithms). Using a CIF places the LO leakage and the undesired sideband outside the signal band at the modulator output where they can be easily removed with a bandpass filter.

![](_page_24_Figure_13.jpeg)

<span id="page-24-3"></span>Figure 63[. ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) Baseband Frequency Response Normalized to Response for 1 MHz

![](_page_25_Figure_2.jpeg)

<span id="page-25-0"></span>Figure 64[. ADL5375-15 B](http://www.analog.com/ADL5375?doc=ADL5375.pdf)aseband Frequency Response Normalized to Response for 1 MHz

In CIF applications, a low-pass filter between the DAC and modulator is still favored to filter out images, noises discussed in the Filtering section as well as to preserve dc bias level from DAC t[o ADL5375-05.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) [Figure 65 s](#page-25-1)hows a fifth order Butterworth filter with a 300 MHz corner frequency and the frequency response of this filter is shown in [Figure 66.](#page-25-2) 

Even a purely differential filter can work well, splitting the filter capacitors into two and grounding at filter topology as like C2 and C4 i[n Figure 65](#page-25-1) divert common mode currents to ground and result in additional common-mode rejection of high frequency signals to a purely differential filter.

![](_page_25_Figure_6.jpeg)

<span id="page-25-1"></span>Figure 65. Recommended DAC Modulator Interface Topology with FC = 300 MHz Fifth-Order, Butterworth Filter

![](_page_25_Figure_8.jpeg)

<span id="page-25-2"></span>Figure 66. Frequency Response for DAC Modulator Interface with 300 MHz Fifth-Order Butterworth Filter

#### **Driving th[e ADL5375-15 w](http://www.analog.com/ADL5375?doc=ADL5375.pdf)ith a TXDAC**

The [ADL5375-15 r](http://www.analog.com/ADL5375?doc=ADL5375.pdf)equires a 1500 mV dc bias and therefore requires a slightly more complex interface that performs a dc level shift on the baseband signals. It is necessary to level-shift the DAC output from a 500 mV dc bias to the 1500 mV dc bias that the [ADL5375-15 r](http://www.analog.com/ADL5375?doc=ADL5375.pdf)equires.

Level-shifting can be achieved with either a passive network or an active circuit. A passive network of resistors is shown in [Figure 67.](#page-25-3) In this network, the dc bias of the DAC remains at 500 mV while the input to th[e ADL5375-15](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is 1500 mV. It should be noted that this passive level-shifting network introduces approximately 2 dB of loss in the ac signal.

![](_page_25_Figure_13.jpeg)

<span id="page-25-3"></span>The active level shifting circuit involves the use of the [ADA4938](http://www.analog.com/ADA4938?doc=ADL3575.pdf) dual-differential amplifier. This device has a VOCM pin that sets the output dc bias. Through this pin, the output commonmode of the amplifier can be easily set to the requisite 1.5 V for biasing th[e ADL5375-15 b](http://www.analog.com/ADL5375?doc=ADL5375.pdf)aseband inputs.

#### **Using th[e AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) DAC For Carrier Feedthrough and Unwanted Sideband Nulling**

The [AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) features an auxiliary DACs (Register 0x42, Register 0x43, Register 0x46, and Register 0x47) or the digital dc offset adjustments (Register 0x3C through Register 0x3F) that can be used to null the carrier feedthrough by applying the dc offset voltage at each main DAC channels. Unwanted sideband suppression can be done by adjusting the I/Q phase (Register 0x38 through Register 0x3B) and DAC FS (Register 0x40 and Register 0x44) registers.

#### <span id="page-26-0"></span>**GSM/EDGE OPERATION**

The performance of the [ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) in a Multi-Carriers GSM/EDGE environment is shown in [Figure 68](#page-26-1) and [Figure 69.](#page-26-2) 

[Figure 68](#page-26-1) illustrates the 6 MHz offset noise floor of the [ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) at the six carriers MCGSM/EDGE(8-PSK) operating condition vs. output power, and [Figure 69](#page-26-2) demonstrates IMD performance of the same six carriers MCGSM/EDGE(8-PSK) for th[e ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) at 950 MHz. It is configured, as shown at [Figure 65,](#page-25-1) for this measurement. Th[e AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) is set at −3 dB digital FS back off,  $F_{DATA} = 368.64$  MSPS, 2× interpolation, and PLL and inverse sync off. Complex IF at 174.32 MHz is generated at NCO of th[e AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) and fed into th[e ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) through a fifth order Butterworth filter. Special care must be taken not to be affected by the noise power of images through proper DAC setup at the selection of IF Frequency, F<sub>DATA</sub>, F<sub>DAC</sub>, and so on for such a low IMD and noise level measurement. Be sure to load clean LO signals and use equipment that allows enough dynamic range capability and noise correction feature to compensated the noise originated by equipment itself.

![](_page_26_Figure_6.jpeg)

<span id="page-26-1"></span>Figure 68[. ADL5375-05 G](http://www.analog.com/ADL5375?doc=ADL5375.pdf)SM/EDGE(8-PSK) 6 Carriers 6 MHz Offset Noise Floor at 950 MHz vs Output Power(1 Carrier/100 KHz), LO Drive = 0 dBm

![](_page_26_Figure_8.jpeg)

<span id="page-26-2"></span>Figure 69[. ADL5375-05 G](http://www.analog.com/ADL5375?doc=ADL5375.pdf)SM/EDGE(8-PSK) 6 Carriers Adjacent and Alternate Channel Power Performance at 950 MHz; Output Power(1 Carrier/100 KHz) = −24.4 dBm LO Drive = 0 dBm

The performance of the [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) in a GSM/EDGE environment is shown in [Figure 70](#page-26-3) and [Figure 71.](#page-27-1) 

[Figure 70](#page-26-3) illustrates the 6 MHz offset noise of th[e ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) and [ADL5375-15 v](http://www.analog.com/ADL5375?doc=ADL5375.pdf)s. output power at 940 MHz. [Figure 71](#page-27-1) demonstrates how the 6 MHz offset noise is affected by variations in LO drive level for both version of the [ADL5375 a](http://www.analog.com/ADL5375?doc=ADL5375.pdf)t 940 MHz.

![](_page_26_Figure_12.jpeg)

<span id="page-26-3"></span>Figure 70. GSM/Edge (8-PSK) 6 MHz Offset Noise at 940 MHz vs. Output Power, LO Drive = 0 dBm

![](_page_27_Figure_2.jpeg)

<span id="page-27-1"></span>Figure 71. GSM/Edge (8-PSK) 6 MHz Offset Noise at 940 MHz vs. LO Drive, Output Power = 0 dBm

#### <span id="page-27-0"></span>**W-CDMA OPERATION**

The [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is suitable for W-CDMA operation. [Figure 72](#page-27-2) an[d Figure 73](#page-27-3) show the adjacent and alternate channel power ratios for the [ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) an[d ADL5375-15,](http://www.analog.com/ADL5375?doc=ADL5375.pdf) respectively, at an LO frequency of 2140 MHz.

![](_page_27_Figure_6.jpeg)

<span id="page-27-2"></span>Figure 72[. ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) Single-Carrier W-CDMA Adjacent and Alternate Channel Power vs. Output Power at 2140 MHz; LO Power = 0 dBm

![](_page_27_Figure_8.jpeg)

<span id="page-27-3"></span>Figure 73[. ADL5375-15](http://www.analog.com/ADL5375?doc=ADL5375.pdf) Single-Carrier W-CDMA Adjacent and Alternate Channel Power vs. Output Power at 2140 MHz; LO Power = 0 dBm

[Figure 72](#page-27-2) an[d Figure 73](#page-27-3) show that both versions of th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) are able to deliver about or better than −73 dB ACPR at an output power of −10 dBm.

[Figure 74](#page-27-4) illustrate the sensitivity of the EVM to variations in LO drive at 2140 MHz for th[e ADL5375-05](http://www.analog.com/ADL5375?doc=ADL5375.pdf) an[d ADL5375-15.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) 

![](_page_27_Figure_12.jpeg)

<span id="page-27-4"></span>Figure 74. Single Carrier W-CDMA Composite EVM vs. LO Drive at 2140 MHz; Output Power = −10 dBm

The EVM exhibits improvements with a local feedthrough nulling operation.

### <span id="page-28-0"></span>**LO GENERATION USING PLLS**

Analog Devices has a line of PLLs that can be used for generating the LO signal. [Table 5 l](#page-28-3)ists the PLLs together with their maximum frequency and phase noise performance.

#### <span id="page-28-3"></span>**Table 5. Analog Devices PLL Selection**

![](_page_28_Picture_369.jpeg)

The [ADF4350](http://www.analog.com/ADF4350?doc=ADL5375.pdf) is a fractional-N PLL which offers broadband operation from 137.5 MHz to 4.4 GHz and contains an integrated high performance VCO.

#### **Table 6. ADF4350 Phase Noise at Various Frequencies**

![](_page_28_Picture_370.jpeg)

### <span id="page-28-1"></span>**TRANSMIT DAC OPTIONS**

Th[e AD9122](http://www.analog.com/AD9122?doc=ADL5375.pdf) recommended in the previous sections of this data sheet is by no means the only DAC that can be used to drive the [ADL5375.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) There are other appropriate DACs, depending on the level of performance required[. Table 7 l](#page-28-4)ists the dual TxDAC offered by Analog Devices.

#### <span id="page-28-4"></span>**Table 7. Dual TxDAC Selection**

![](_page_28_Picture_371.jpeg)

All DACs listed have nominal bias levels of 0.5 V and use the same simple DAC modulator interface that is shown i[n Figure 75.](#page-29-1) 

### <span id="page-28-2"></span>**MODULATOR/DEMODULATOR OPTIONS**

[Table 8 l](#page-28-5)ists other Analog Devices modulators and demodulators.

#### <span id="page-28-5"></span>**Table 8. Modulator/Demodulator Options**

![](_page_28_Picture_372.jpeg)

7052

## <span id="page-29-0"></span>EVALUATION BOARD

Populated RoHS-compliant evaluation boards are available for evaluation of the [ADL5375.](http://www.analog.com/ADL5375?doc=ADL5375.pdf) Th[e ADL5375 p](http://www.analog.com/ADL5375?doc=ADL5375.pdf)ackage has an exposed paddle on the underside. This exposed paddle should be soldered to the board for good thermal and electrical grounding. The evaluation board is designed to minimize LO feedthrough to RFOUT through PCB by placing LO block on the underside. And it can be configured to allow differential LO driving through balun or direct interfacing to the PLL evaluation board. It also reserves component pads in its LO path to accommodate a harmonic filter. One side placement of baseband inputs is to interface directly to DAC evaluation board. The [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) evaluation board also includes an RF driver amplifier. The modulator output can be measured directly at the MOD\_OUT SMA connector. Alternatively, by removing R1, and installing a 0  $\Omega$  resistor in the R2 pad, the modulator's output can be fed to the RF driver amplifier.

The evaluation board ships, installed with a[n ADL5320](http://www.analog.com/ADL5320?doc=ADL5375.pdf) driver amplifier (400 MHz to 2700 MHz RF driver amplifier). This device requires external matching components (C100 and C101) and is tuned by default for operation from 1805 MHz to 2170 MHz. For details on tuning component values for other frequencies, please refer to th[e ADL5320 d](http://www.analog.com/ADL5320?doc=ADL5375.pdf)ata sheet (the driver amplifier section of the [ADL5375 E](http://www.analog.com/ADL5375?doc=ADL5375.pdf)valuation Board is identical to the [ADL5320](http://www.analog.com/ADL5320?doc=ADL5375.pdf) Evaluation Board). For higher frequency operation, th[e ADL5320](http://www.analog.com/ADL5320?doc=ADL5375.pdf) should be replaced by th[e ADL5321,](http://www.analog.com/ADL5321?doc=ADL5375.pdf) which is specified to operate from 2.3 GHz to 4 GHz. If a broadband matched device is desired, th[e ADL5601 \(](http://www.analog.com/ADL5601?doc=ADL5375.pdf)15 dB) o[r ADL5602](http://www.analog.com/ADL5602?doc=ADL5375.pdf) (20 dB) broadband gain blocks can be used.

![](_page_29_Figure_6.jpeg)

<span id="page-29-1"></span>Figure 75[. ADL5375 E](http://www.analog.com/ADL5375?doc=ADL5375.pdf)valuation Board Schematic

![](_page_30_Picture_346.jpeg)

### **Table 9. Evaluation Board Description and Configuration Options**

![](_page_31_Picture_2.jpeg)

Figure 76. Evaluation Board Layout, Top Layer

![](_page_31_Figure_4.jpeg)

Figure 77. Evaluation Board Layout, Bottom Layer

#### <span id="page-31-0"></span>**Thermal Grounding and Evaluation Board Layout**

The package for the [ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) features an exposed paddle on the underside that should be well soldered to a low thermal and electrical impedance ground plane. This paddle is typically soldered to an exposed opening in the solder mask on the evaluation board. [Figure 78 i](#page-31-1)llustrates the dimensions used in the layout of th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) footprint on th[e ADL5375 E](http://www.analog.com/ADL5375?doc=ADL5375.pdf)valuation Board (1 mil. = 0.0254 mm).

Notice the use of nine via holes on the exposed paddle. These ground vias should be connected to all other ground layers on the evaluation board to maximize heat dissipation from the device package.

![](_page_31_Figure_9.jpeg)

<span id="page-31-1"></span>Figure 78. Dimensions for Evaluation Board Layout for th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) Package

Under these conditions, the thermal impedance of th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) was measured to be approximately 30°C/W in still air.

## <span id="page-32-0"></span>CHARACTERIZATION SETUP

![](_page_32_Figure_3.jpeg)

Figure 79. Characterization Bench Setup

<span id="page-32-1"></span>The primary setup used to characterize th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is shown in [Figure 79.](#page-32-1) This setup was used to evaluate the product as a single-sideband modulator. The aeroflex signal generator supplied the LO and differential I and Q baseband signals to the device under test (DUT). The typical LO drive was 0 dBm. The I-channel is driven by a sine wave, and the Q-channel is driven by a cosine wave. The lower sideband is the single-sideband (SSB) output.

The majority of characterization for th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) was performed using a 1 MHz sine wave signal with a 500 mV [\(ADL5375-05\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf) or 1500 mV [\(ADL5375-15\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf) common-mode voltage applied to the baseband signals of the DUT. The baseband signal path was calibrated to ensure that the  $V_{\rm IOS}$  and  $V_{\rm QOS}$  offsets on the baseband inputs were minimized as close as possible to 0 V before connecting to the DUT. See th[e Carrier Feedthrough](#page-21-1) Nulling section for the definitions of VIOS and VQOS.

![](_page_33_Figure_2.jpeg)

Figure 80. Setup for Baseband Frequency Sweep and Undesired Sideband Nulling

<span id="page-33-0"></span>The setup used to evaluate baseband frequency sweep and undesired sideband nulling of th[e ADL5375](http://www.analog.com/ADL5375?doc=ADL5375.pdf) is shown i[n Figure 80.](#page-33-0)  The interface board has circuitry that converts the single-ended I input and Q input from the arbitrary function generator to differential I and Q baseband signals with a dc bias of 500 mV

[\(ADL5375-05\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf) or 1500 mV [\(ADL5375-15\)](http://www.analog.com/ADL5375?doc=ADL5375.pdf). Undesired sideband nulling was achieved through an iterative process of adjusting amplitude and phase on the Q-channel. Se[e Sideband](#page-21-2)  [Suppression Optimization](#page-21-2) section for a detailed description on sideband nulling.

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## <span id="page-34-0"></span>OUTLINE DIMENSIONS

![](_page_34_Figure_3.jpeg)

**COMPLIANT TO JEDEC STANDARDS MO-220-WGGD.**

Figure 81. 24-Lead Lead Frame Chip Scale Package [LFCSP\_WQ] 4 mm × 4 mm Body, Very Very Thin Quad  $(CP-24-7)$ Dimensions shown in millimeters

### <span id="page-34-1"></span>**ORDERING GUIDE**

![](_page_34_Picture_212.jpeg)

 $1 Z =$  RoHS Compliant Part.

## **NOTES**

![](_page_35_Picture_3.jpeg)

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